

# SMT 2017 Cleaning System for Bare Boards



# Residue-free Cleaning of Bare Boards

The trend in high-end productions like the automotive industry, communication, aircraft and medical industry is towards „zero defects“.

This requirement is driven by various factors like i.e. miniaturisation of components, an enhanced process control and customer compliance.

Approximately 70% of all defects in the SMT process occur during the solder paste print.

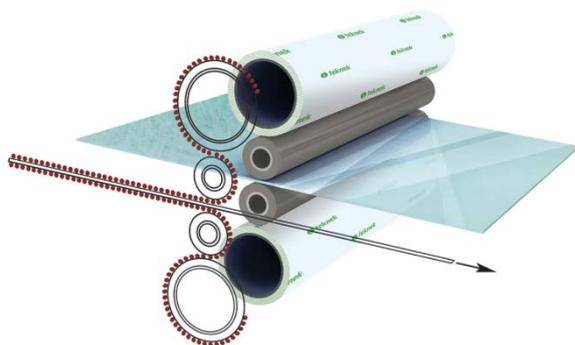
The quality of the print is directly related to the level of contamination on the board as it enters printing.

The SMT2017 remedies this variable from the process by cleaning the surface of the pads just before application of solder

## Cleaning method:

The contamination on the PCBs will be absorbed from the elastomer roll and directly transferred to an adhesive roll. Thus, no particles will be emitted into the environment.

The adhesive roll consists of single sheets. As soon as one sheet is too much contaminated, it will be simply removed - no cutting, no tearing off, not tool necessary.



Typical applications for our cleaning systems from Teknek are:

- Before solder printing: By removing the contamination blocking of the stencils will be avoided and the quality of the paste print will be dramatically enhanced.
- After laser marking to remove dust from the PCBs.

Because of its compact design the SMT2017 can be easily integrated into the production line.

The SMT2017 is available in two different models, the first one for PCBs with a max. width of 400 mm and the second one for boards up to 600 mm width. You have the choice between single-sided cleaning or alternatively also double-sided cleaning of your boards.

The SMT cleaning systems from Teknek are furthermore equipped with a ionizer at the output. With this and the especially developed Nanoclean™ adhesive rolls the remaining electrostatic charge can be reduced down to about 35 V.

A new, faster PLC from ProFace enables an easy operation and setup of the system without special training.

The new software has the ability to store 250 different board programs making change over quick and easy.

## SMT2017 Cleaning system – Technical Specifications

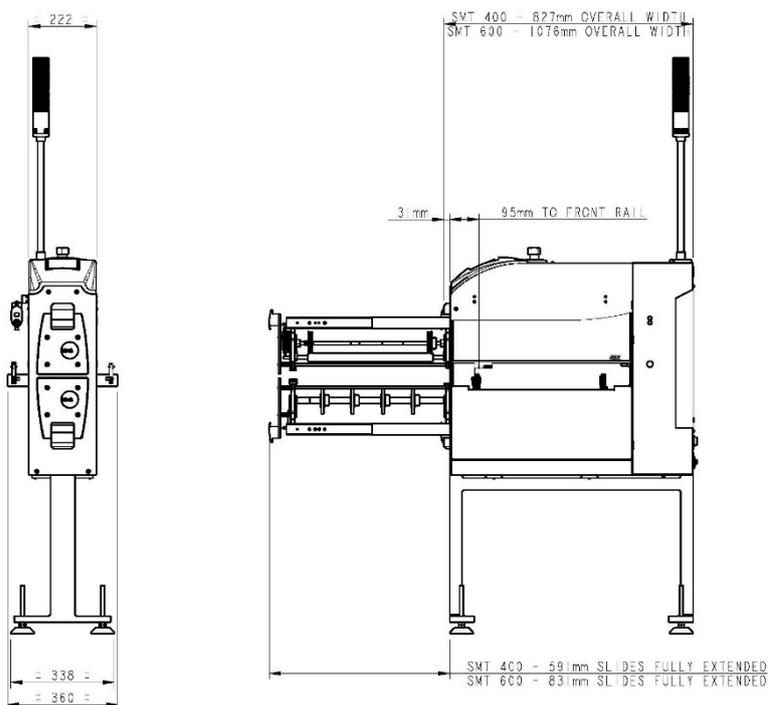
Description	
Two cleaning widths	40 – 400 mm 40 – 600 mm
Operation modes	Double side cleaning and bypass or single side cleaning and bypass
Elastomer rollers	Nanoclean™ 20.20
Adhesive rollers	ARLS – Low Static Adhesive
Progressing speed	1-40 m/min.
Pass line height	900 +/-50 mm
Power Supply	Universal Power Supply
Pneumatic pressure	5-7 bar oil free compressed air
ESD compatibility	
Machine	ANSI / ESDs 20.20 -2014
Nanoclean™ 20.20	ANSI / ESDs 6.1 - 2014

Alle TEKNEK Elastomer rollers are compliant with ISO 7123 class A  
 Alle TEKNEK Adhesive rollers are compliant with FINAT

### Usable board sizes and thicknesses

		SMT2017/400	SMT2017/600
Double side cleaning	Min - Max Length	98mm - N/A	98mm - N/A
	Min - Max Width	40mm - 400mm	40mm - 600mm
	Min - Max Thickness	0.6mm - 3.2mm	0.6mm - 3.2mm
Bypass without cleaning	Min - Max Length	120mm - N/A	120mm - N/A
	Min - Max Width	40mm - 400mm	40mm - 600mm
	Min - Max Thickness	0.6mm - 3.2mm	0.6mm - 3.2mm
Single side cleaning	Min - Max Length	50mm - N/A	50mm - N/A
	Min - Max Width	40mm - 400mm	40mm - 600mm
	Min - Max Thickness	0.6mm - 3.2mm	0.6mm - 3.2mm
Bypass without cleaning	Min - Max Length	50mm - N/A	50mm - N/A
	Min - Max Width	40mm - 400mm	40mm - 600mm
	Min - Max Thickness	0.6mm - 3.2mm	0.6mm - 3.2mm

### Dimensions of SMT2017



## Our Product Portfolio



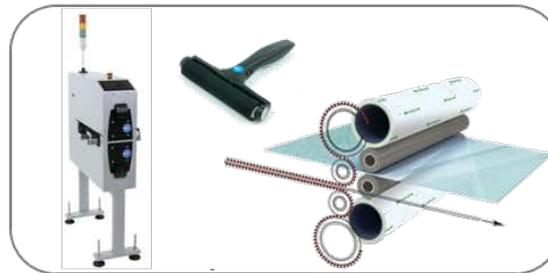
Feeding Technology



Label Feeder, Labels and Marking Solutions



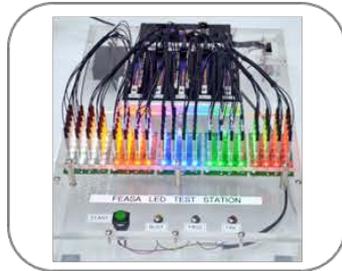
Special Applications



Bare Board Cleaning



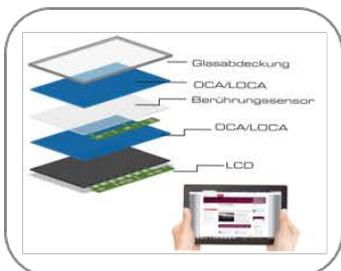
In-System Programming



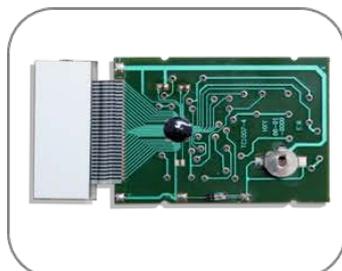
LED Analysis



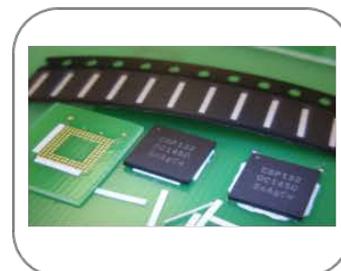
Reflow Inline Camera



Optical Bonding



Thermal Bonding



Place-N-Bond